

## **DATA ITEM DESCRIPTION (DID)**

### **Title: Lead-Free Control Plan (LFCP)**

**Number:** DI-MGMT- 81772

**AMSC Number:** N9072

**DTIC Applicable:** N/A

**Office of Primary Responsibility:** SEA04RM

**Applicable Forms:** N/A

**Approval Date:** 20090612

**Limitation:**

**GIDEP Applicable:** N/A

**Use/Relationship:** The Lead-Free Control Plan (LFCP) will be used to obtain essential information from contractors on how they plan to manage the risk of lead-free solders or finishes used in their products during the program's lifecycle.

This DID contains the format and content preparation instruction for the data product generated by the specific and discrete task requirement as delineated in the contract.

This DID is applicable to all new contracts and solicitations that acquire electronic systems including weapons systems containing electronic components as well as rework or repair of electronic systems or components.

The DID may also be applicable to systems already in production for major changes and block upgrades.

The reference documents cited in this DID, GEIA-STD-0005-1, "Performance Standard for Aerospace and High Performance Electronic Systems Containing Lead-Free Solder" and GEIA –STD-0005-2, "Standard for Mitigating the Effects of Tin Whiskers in Aerospace and High Performance Electronic Systems", may be obtained from: Government Electronics and Information Technology Association, 2500 Wilson Boulevard, Suite 1100, Arlington, VA 22201, or as specified in the contract.

### **Requirements:**

1. Reference documents. The applicable issue of any documents cited herein, including their approval dates and dates of any applicable amendments, notices, and revisions, shall be as specified in the contract.

2. Format. The LFCP shall be presented in the contractor's own format.

3. Content. The LFCP shall contain all of the information specified in GEIA-STD-0005-1 and GEIA-STD-0005-2.

3.1 Lead-Free Solder and Finishes. The plan shall address all lead-free solders and lead-free tin finishes in delivered products.

3.1.1 Reliability. The processes and materials utilizing lead-free solder or finishes shall be identified as capable of producing items that meet product reliability requirements.

3.1.2 Configuration Control and Product Identification. The configurations of all systems, assemblies, subassemblies, and parts shall be included and identified by version and applicable configuration identifier.

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3.1.3 Risks and Limitations of use. Any risks or limitations on the use of the products due to the incorporation of lead-free solder or finishes shall be identified along with information on how to manage those risks or limitations.

3.1.4 Tin (Sn) Whiskers. Any harmful effects of Sn whiskers resulting from use of lead-free tin shall be addressed.

3.2 The plan shall contain any recommendations or changes to the product design and any contract modifications required to comply with the LFCP.

End of DI-MGMT- 81772